

## D. Thin Film Process Technology **분과**

2017년 2월 14일 (화), 10:10-11:40  
Room A (에메랄드, 2층)

### [TA2-D] Emerging Thin Film Technology

좌장: 김형섭(성균관대학교), 윤성민(경희대학교)

<b>TA2-D-1</b> 10:10-10:25	<b>The Low Temperature and Ion Implantation-Based Large-Scale Wafer Bonding for the Monolithic 3D Integration Platform</b> HoonHee Han, Yu-Rim Jeon, Donghwan Lim, Jaeho Lee, So Hyun Kim, and Changhwan Choi <i>Division of Materials Science and Engineering, Hanyang University</i>
<b>TA2-D-2</b> 10:25-10:40	<b>Hardmask Carbon의 Raman Band와 물성과의 상호관계 평가</b> 김경원, 이준필, 최민기, 송병목, 연태원, 광경익, 손성규, 이기정 <i>SK하이닉스</i>
<b>TA2-D-3</b> 10:40-10:55	<b>유기금속화합물-반도체 나노소재 복합화를 통한 소자성능 향상 연구</b> 전인수 <sup>1,2</sup> , 김성준 <sup>1</sup> , 송우석 <sup>1</sup> , 명성 <sup>1</sup> , 이선숙 <sup>1</sup> , 임종선 <sup>1</sup> , 안기석 <sup>1</sup> <i><sup>1</sup>한국화학연구원 박막재료연구센터, <sup>2</sup>홍익대학교 신소재공학과</i>
<b>TA2-D-4</b> 10:55-11:10	<b>Advanced Titanium Nitride (TiN) Film as a Metal Hard Mask (MHM) by VHF(Very High Frequency) Sputtering for 1X nm Node and Beyond</b> Byeong-Hwa Jeong, Eun-Kyoung Ma, Chang-Min Jeong, Hyun-Ji Cho, Jouji Hiroishi, Seung-Su Choi, and In-Sang Jeon <i>Korea Institute for Super Materials (KISM), ULVAC KOREA, Co.Ltd.</i>
<b>TA2-D-5</b> 11:10-11:25	<b>Non-Planar Split-Gate Ambipolar Organic Thin-Film Transistors and Logic Circuits</b> Hocheon Yoo and Jae-Joon Kim <i>Department of Creative IT engineering, Pohang University of Science and Technology</i>
<b>TA2-D-6</b> 11:25-11:40	<b>The Process of Wafer Bonding and De-Bonding for Monolithic 3D Technology</b> Yu-Rim Jeon, HoonHee Han, and Changhwan Choi <i>Division of Materials Science and Engineering, Hanyang University</i>